

# MBR230LSF

Surface Mount Schottky Barrier Rectifier
Reverse Voltage :30 V / Forward Current: 2.0A

#### Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

#### **PINNING**

PIN	DESCRIPTION					
1	Cathode					
2	Anode					



Absolute Maximum Ratings and Electrical characteristics Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

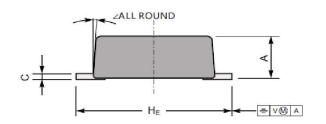
Parameter	Symbols	MBR230LSF	Units	
Maximum Repetitive Peak Reverse Voltage	Verm	30	V	
Maximum RMS voltage	V <sub>RMS</sub>	28	V	
Maximum DC Blocking Voltage	V <sub>pc</sub>	40	V	
Maximum Average Forward Rectified Current	I <sub>F(AV)</sub>	2.0		
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I <sub>FSM</sub>	50	A	
Max Instantaneous Forward Voltage at 2 A	V <sub>F</sub>	0.55	v	
Maximum DC Reverse Current T <sub>a</sub> = 25°C at Rated DC Reverse Voltage T <sub>a</sub> =100°C	I <sub>R</sub>	0.5 10	mA	
Typical Junction Capacitance 1)	C,	220	pF	
Operating Junction Temperature Range	Tj	-55~+125	°C	
Storage Temperature Range	T <sub>stg</sub>	-55 ~ +150	°C	

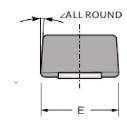
1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

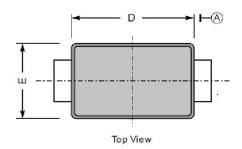
REV.08 1 of 3

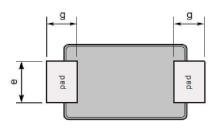
## PACKAGE OUTLINE

## Plastic surface mounted package; 2 leads





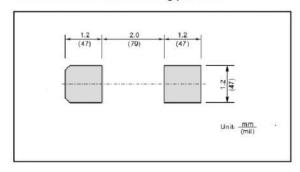




Bottom View

UNIT		Α	С	D	E	е	g	HE	2
mm —	max	1.1	0.20	2.9	1.9	1.1	0.9	3.8	7°
	min	0.9	0.12	2.6	1.7	0.8	0.7	3.5	
mil –	max	43	7.9	114	75	43	35	150	
	min	35	4.7	102	67	31	28	138	

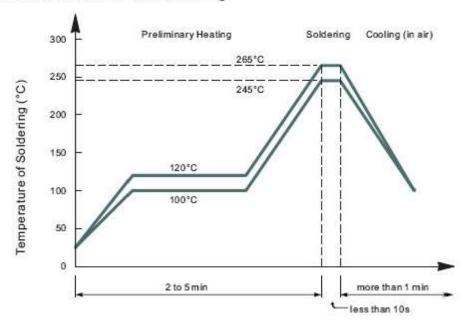
#### The recommended mounting pad size



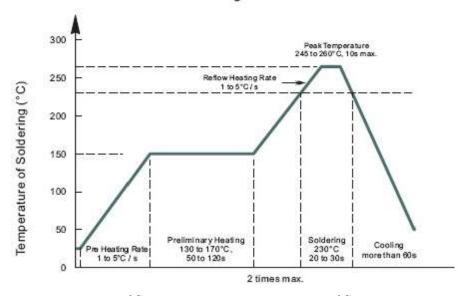
REV.08 2 of 3



## · Recommended condition of flow soldering



#### · Recommended condition of reflow soldering



Recommended peak temperature is over  $245^{\circ}\mathrm{C}$ , If peak temperature is below  $245^{\circ}\mathrm{C}$ , you may adjust the following parameters; time length of peak temperature (longer), time length of soldering (longer), thickness of solder paste (thicker)

• Condition of hand soldering: Temperature: 350°C Time: 3s max. Times: one time

• Remark: Lead free solder paste (96.5Sn/3.0Ag/0.5Cu)